L Number	Hits	Search Text	DB	Time stamp
3	0	("863030.ap.").PN.	USPAT; US-PGPUB; EPO; JPO;	2003/03/27 11:23
4	3	863030.ap.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/03/27 11:46
5	2	("5451818").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/03/27
6	0	("MMIC.ti,ab,clm. and thick adj film adj capacitor").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/03/27 12:04
7	1	MMIC.ti,ab,clm. and thick adj film adj capacitor	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/03/27 12:11
8	0	MMIC.ti,ab,clm. and air near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 12:12
9	0	MMIC.ti,ab,clm. and (spacing or air) near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 12:13
10	0	,	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 . 12:15
11	13	1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 12:16
12	0	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver) and (257/\$6.ccls. or 438/\$6.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 12:17
13	2		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 12:19
14	13		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/27 17:05
15	2	488721.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:12

16	37	LTCC and MMIC	USPAT;	2003/03/27	Ī
			US-PGPUB;	13:13	
			EPO; JPO;		ı
			DERWENT;		
			IBM_TDB		
17	0	LTCC near12 transfer adj tape and MMIC	USPAT;	2003/03/27	
			US-PGPUB;	13:13	ĺ
			EPO; JPO;		l
			DERWENT;		
	}		IBM_TDB		l
18	4	LTCC and transfer adj tape and MMIC	USPAT;	2003/03/27	l
			US-PGPUB;	13:18	l
			EPO; JPO;		l
			DERWENT;		l
			IBM_TDB	2002 (02 (27	l
19	4	LTCC and transfer adj tape and	USPAT;	2003/03/27	l
		(monolithic adj microwave adj integrated	US-PGPUB;	13:20	İ
		adj circuit or MMIC)	EPO; JPO; DERWENT;		l
					l
20	7	/low and temperature and go fixed and	IBM_TDB USPAT;	2003/03/27	l
20	/	(low adj temperature adj co-fired adj ceramic or LTCC) and transfer adj tape	US-PGPUB;	14:43	1
		and (monolithic adj microwave adj	EPO; JPO;	11.13	1
		integrated adj circuit or MMIC)	DERWENT;		
		Integrated adj critodic or ratio;	IBM TDB		
21	170	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27	l
	1,3	resistor	US-PGPUB;	14:44	
		TOBIBOOI	EPO; JPO;		
			DERWENT;		
			IBM TDB		
22	73	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27	
		resistor.ti,ab,clm.	US-PGPUB;	14:44	
		,	EPO; JPO;		
			DERWENT;		
			IBM_TDB		
23	5	MMIC.ti,ab,clm. and capacitor same	USPAT;	2003/03/27	
		resistor.ti,ab,clm. and	US-PGPUB;	14:45	ĺ
		transceiver.ti,ab,clm.	EPO; JPO;	-	
			DERWENT;		
			IBM_TDB		ı
24	1427	1 , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/03/27	ı
		(455/73)).CCLS.	US-PGPUB;	17:07	ı
			EPO; JPO;		ı
			DERWENT;		
0.5	0.1	///057/077) /057/700\	IBM_TDB	2002/02/27	
25	81	(((257/277) or (257/728) or	USPAT;	2003/03/27	
	1	(455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj	US-PGPUB; EPO; JPO;	17.10	
		circuit).ti,ab,clm.	DERWENT;		
		CIICUIC, CI, GD, CIIII.	IBM TDB		
26	8	(((257/277) or (257/728) or	USPAT;	2003/03/27	
		(455/73)).CCLS.) and (mmic or monolithic	US-PGPUB;	17:10	
		adj microwave adj integrated adj	EPO; JPO;		
		circuit).ti,ab,clm. and transceiver	DERWENT;		
		, ,	IBM TDB		
-	0	mmic.ti. and transceiver.clm.	USPAT;	2002/10/20	
			US-PGPUB;	16:25	
			EPO; JPO;		
			DERWENT;		-
			IBM_TDB		
-	15	mmic.ti. and transceiver	USPAT;	2002/09/14	
			US-PGPUB;	14:12	
			EPO; JPO;		
			DERWENT;		
	1		IBM_TDB		
-	1	mmic.ti. and transceiver and (tuned or	USPAT;	2002/09/14	
		tuning)	US-PGPUB;	14:13	
			EPO; JPO;		
			DERWENT;	1	
1			IBM_TDB		1

-	0	mmic.ti. and transceiver.ti,ab,clm. and	USPAT;	2002/09/14	
		(tuned or tuning).ti,ab.clm.	US-PGPUB;	14:15	
			EPO; JPO; DERWENT;		
			IBM TDB		
-	2	\	USPAT;	2002/09/14	
		and transceiver.ti,ab,clm. and (tuned or	US-PGPUB;	14:44	
		tuning).ti,ab.clm.	EPO; JPO;		
			DERWENT;		
_	0	(mmic or microwave adj monolithic).ti.	IBM_TDB	2002/00/14	
		and transceiver.ti, ab, clm. and	USPAT; US-PGPUB;	2002/09/14	
Ì		438/\$6.ccls.	EPO; JPO;	14.44	
			DERWENT;		- 1
Ì			IBM_TDB		
-	20		USPAT;	2002/09/14	
		and 438/\$6.ccls.	US-PGPUB;	14:44	Ì
i			EPO; JPO;		
			DERWENT; IBM TDB		
-	370	integrated adj circuit adj board.ti.	USPAT;	2002/09/17	
		, , , , , , , , , , , , , , , , , , ,	US-PGPUB;	12:07	
			EPO; JPO;		
			DERWENT;		
	7		IBM_TDB		-
-	/	integrated adj circuit adj board.ti. and integrated adj circuit adj board.clm.	USPAT;	2002/09/17	
		integrated adj circuit adj board.cim.	US-PGPUB; EPO; JPO;	12:08	
			DERWENT;		
			IBM TDB		İ
-	634	(455/73).CCLS.	USPAT;	2002/10/20	
			US-PGPUB;	16:25	- [
			EPO; JPO;		
			DERWENT;		
-	147	(257/277).CCLS.	IBM_TDB USPAT;	2002/10/20	
		(10 (, 1 / 1 / 1 / 1 / 1 / 1 / 1 / 1 / 1 / 1	US-PGPUB;	16:25	
		•	EPO; JPO;	10.23	
			DERWENT;		
	F.F.2	(057 (700)	IBM_TDB		١
-	551	(257/728).CCLS.	USPAT;	2002/10/20	
			US-PGPUB; EPO; JPO;	16:26	
			DERWENT;		
			IBM TDB		
_	1978	(mmic or monolithic adj microwave adj	USPAT;	2002/10/20	
		integrated adj circuit).ti,ab,clm.	US-PGPUB;	16:26	1
			EPO; JPO;		
			DERWENT;		
_	1325	((455/73).CCLS.) or ((257/277).CCLS.) or	IBM_TDB USPAT;	2002/10/20	
		((257/728).CCLS.)	US-PGPUB;	16:27	
			EPO; JPO;		
			DERWENT;		İ
_	70	//www.dom.com.com.com.com.com.com.com.com.com.c	IBM_TDB		
_	/0	((mmic or monolithic adj microwave adj	USPAT;	2002/10/20	
	.	integrated adj circuit).ti,ab,clm.) and (((455/73).CCLS.) or ((257/277).CCLS.) or	US-PGPUB; EPO; JPO;	16:27	
		((257/728).CCLS.))	DERWENT;		
		,,	IBM TDB		
-	3233	((mmic or monolithic adj microwave adj	USPAT;	2002/10/20	
		integrated adj circuit).ti,ab,clm.) or	US-PGPUB;	16:27	
		(((455/73).CCLS.) or ((257/277).CCLS.) or	EPO; JPO;		
		((257/728).CCLS.))	DERWENT;		
_	221	(((mmic or monolithic adj microwave adj	<pre>IBM_TDB USPAT;</pre>	2002/10/20	
		integrated adj circuit).ti,ab,clm.) or	US-PGPUB;	16:28	
		(((455/73).CCLS.) or ((257/277).CCLS.) or	EPO; JPO;		
		((257/728).CCLS.))) and	DERWENT;		
		transceiver.ti,ab,clm.	IBM TDB		

Γ <u>-</u>	<u> </u>	((((mmic or monolithic adj microwave adj	USPAT;	2002/10/20
_	1	integrated adj circuit).ti,ab,clm.) or	US-PGPUB;	16:29
		(((455/73).CCLS.) or ((257/277).CCLS.) or	EPO; JPO;	10.25
		((257/728).CCLS.))) and	DERWENT;	
		transceiver.ti,ab,clm.) and transfer adj	IBM TDB	
		tape	15.1_155	
_	2	("5545924").PN.	USPAT;	2002/10/20
		,	US-PGPUB;	17:13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("6124636").PN.	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	"5423080"	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("5423080").PN.	USPAT;	2002/10/20
			US-PGPUB;	17:14
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	1 '	USPAT;	2002/10/20
		US-6424074-\$ or US-6124765-\$ or	US-PGPUB;	17:34
		US-6278337-\$ or US-6278159-\$ or	DERWENT	
	1	US-5545924-\$ or US-6268779-\$ or		
		US-6073484-\$ or US-6441449-\$ or		
		US-6201728-\$ or US-6257058-\$).did. or		
		(US-20010001224-\$).did. or (EP-712534-\$		
		or EP-504020-\$ or JP-11214578-\$ or		
	_	WO-200075762-\$ or WO-200223674-\$).did.		
-	1	((US-5423080-\$ or US-6124636-\$ or	USPAT;	.2002/10/20
		US-6424074-\$ or US-6124765-\$ or	US-PGPUB;	17:35
		US-6278337-\$ or US-6278159-\$ or	DERWENT	
		US-5545924-\$ or US-6268779-\$ or		
		US-6073484-\$ or US-6441449-\$ or		
		US-6201728-\$ or US-6257058-\$).did. or		
		(US-20010001224-\$).did. or (EP-712534-\$ or EP-504020-\$ or JP-11214578-\$ or		
		WO-200075762-\$ or WO-200223674-\$).did.)		
		and transfer adj tape		
_	2724	mmic or monolithic adj microwave adj	USPAT;	2002/10/20
_	2/24	intergated adj circuit and transfer adj	US-PGPUB;	17:35
		tape	DERWENT	17.33
_	5		USPAT;	2002/10/20
		integrated adj circuit) and transfer adj	US-PGPUB;	17:36
		tape	DERWENT	17.50
_	19		USPAT;	2002/10/20
	19	US-5423080-\$ or US-6124636-\$ or	US-PGPUB;	19:33
		US-5545924-\$ or US-6257058-\$ or	DERWENT	17.33
		US-6278159-\$ or US-6278337-\$ or	DIII.	
		US-6201728-\$ or US-6124765-\$ or		
		US-6424074-\$ or US-6073484-\$ or		
		US-6268779-\$).did. or		
		(US-20010001224-\$).did. or (EP-504020-\$		
		or JP-11214578-\$ or EP-712534-\$ or		
		WO-200223674-\$ or WO-200075762-\$).did.		
	L			1

-	8	((US-5451818-\$ or US-6441449-\$ or	USPAT;	2002/10/20
		US-5423080-\$ or US-6124636-\$ or	US-PGPUB;	20:05
		US-5545924-\$ or US-6257058-\$ or	EPO; JPO;	
		US-6278159-\$ or US-6278337-\$ or	DERWENT;	
-		US-6201728-\$ or US-6124765-\$ or	IBM_TDB	
		US-6424074-\$ or US-6073484-\$ or		
		US-6268779-\$).did. or		
		(US-20010001224-\$).did. or (EP-504020-\$		
		or JP-11214578-\$ or EP-712534-\$ or		
		WO-200223674-\$ or WO-200075762-\$).did.)		
		and thickness		
-	18	, (,,,	USPAT;	2002/10/20
		and ((thick or thickness) same mil)	US-PGPUB;	20:07
			EPO; JPO;	
			DERWENT;	
		/14414 14 - 1 1	IBM_TDB	
_	0	(USPAT;	2002/10/20
		and ((thick or thickness) near12 mil	US-PGPUB;	20:08
		near12 base)	EPO; JPO;	
			DERWENT;	
	1.7	/	IBM_TDB	
	17		USPAT;	2002/10/20
		and ((thick or thickness) near12 mil)	US-PGPUB;	20:12
	1		EPO; JPO;	
	1		DERWENT;	
_	25	cte near4 gaas	IBM_TDB	2002/10/22
	43	cue meany gaas	USPAT;	2002/10/20
			US-PGPUB;	20:50
			EPO; JPO;	
			DERWENT;	
_	2	("5451818").PN.	IBM_TDB USPAT;	2002/10/20
		(3431010).EN.	US-PGPUB;	20:50
			EPO; JPO;	20:50
			DERWENT;	
			IBM TDB	
_	2	("5451818").PN.	USPAT;	2002/10/21
		(0101010 / 11111	US-PGPUB;	07:56
			EPO; JPO;	07.30
			DERWENT;	
			IBM TDB	
-	0	("solder near3 MMIC adj chip").PN.	USPAT;	2002/10/21
		3 1 , ====	US-PGPUB;	07:56
	1		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	7	solder near3 MMIC adj chip	USPAT;	2002/10/21
			US-PGPUB;	08:12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	silver adj epoxy near6 MMIC	USPAT;	2002/10/21
			US-PGPUB;	08:13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	silver adj epoxy near12 chip and	USPAT;	2002/10/21
		MMIC.ti,ab,clm.	US-PGPUB;	08:14
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5	silver adj epoxy near12 (die or chip) and	USPAT;	2002/10/21
		(monolithic adj microwave or	US-PGPUB;	08:15
		MMIC).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0000 (00 (5.5
_	6	silver adj epoxy near12 (die or chip) and	USPAT;	2002/10/21
]	(monolithic adj microwave or MMIC)	US-PGPUB;	08:21
]		EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	l İ

-	16	solder near4 preform and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 08:21
-	13	solder near4 preform and MMIC.ti,ab,clm.	IBM_TDB USPAT; US-PGPUB;	2002/10/21 08:31
			EPO; JPO; DERWENT; IBM TDB	
_	1	<pre>(radio-frequency or radio adj frequency or rf) adj (lid or cover) near15 (MMIC or monolithic adj microwave)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 08:34
-	1	(radio-frequency or radio adj frequency or rf or kovar) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 08:34
-	2	or rf or kovar) near4 (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:03
-	158	through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05
	20	through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05
_		through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:07
-	6	isolating) adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:11
-	47	isolation adj via.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:12
-	1	isolation adj via.ti,ab,clm. and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:12
-	6	isolation adj via.ti,ab,clm. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:17
-	1	(isolation adj via or isolation adj trench).ti,ab,clm. and (chip or die) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 09:18
-	3097	mmic and sti or isolation adj trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19

			110000	1 2002 /10 /21
_	0	(isolation adj trench or sti) same mmic	USPAT;	2002/10/21
			US-PGPUB;	09:19
			EPO; JPO;	
			DERWENT;	
	110		IBM_TDB	2002/10/21
_	112		USPAT;	2002/10/21
		and (integrated adj circuit or	US-PGPUB;	09:20
		ic).ti,ab,clm.	EPO; JPO;	
			DERWENT;	
	.		IBM_TDB	2002/10/21
-	4	(isolation adj trench or sti) and mmic	USPAT;	2002/10/21
			US-PGPUB;	09:31
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	222242424
_	12	-F1	USPAT;	2002/10/21
		circuit and mmic	US-PGPUB;	10:00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	("5451818").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("5319329").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:01
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
_	2	("5239685").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:01
			EPO; JPO;	
			DERWENT;	
		(#E 40 C120 H) DV	IBM_TDB	2002/10/21
_	2	_("5406122").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:02
			EPO; JPO;	
			DERWENT;	
	2	(#5040079#) DN	IBM_TDB	2002/10/21
_	2	("5049978").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:02
			EPO; JPO;	
			DERWENT;	
		(UCA26696U) DN	IBM_TDB	2002/10/21
_	2	("6426686").PN.	USPAT;	2002/10/21
			US-PGPUB;	10:02
			EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	